IGBT - Short-Circuit Rated

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Non-Punch Through (NPT) Trench construction, and provides superior performance in demanding switching applications. Offering both low on state voltage and minimal switching loss, the IGBT is well suited for motor drive control and other hard switching applications. Incorporated into the device is a rugged co-packaged reverse recovery diode with a low forward voltage.

Features

- Low Saturation Voltage Resulting in Low Conduction Loss
- Low Switching Loss in Higher Frequency Applications
- Soft Fast Reverse Recovery Diode
- 5 us Short Circuit Capability
- Excellent Current versus Package Size Performance Density
- This is a Pb-Free Device

Typical Applications

- White Goods Appliance Motor Control
- General Purpose Inverter
- AC and DC Motor Control

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	600	V
Collector current @ Tc = 25°C @ Tc = 100°C	I _C	30 15	Α
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	120	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	l _F	30 15	Α
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	120	Α
Gate-emitter voltage	V_{GE}	±20	V
Power dissipation @ Tc = 25°C @ Tc = 100°C	P _D	117 47	W
Short circuit withstand time V_{GE} = 15 V, V_{CE} = 400 V, T_{J} \leq +150°C	t _{SC}	5	μs
Operating junction temperature range	TJ	-55 to +150	ô
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

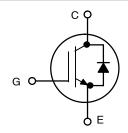
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

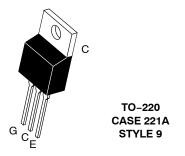


ON Semiconductor®

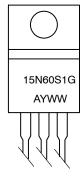
http://onsemi.com

15 A, 600 V V_{CEsat} = 1.5 V





MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB15N60S1EG	TO-220 (Pb-Free)	50 Units / Rail

THERMAL CHARACTERISTICS

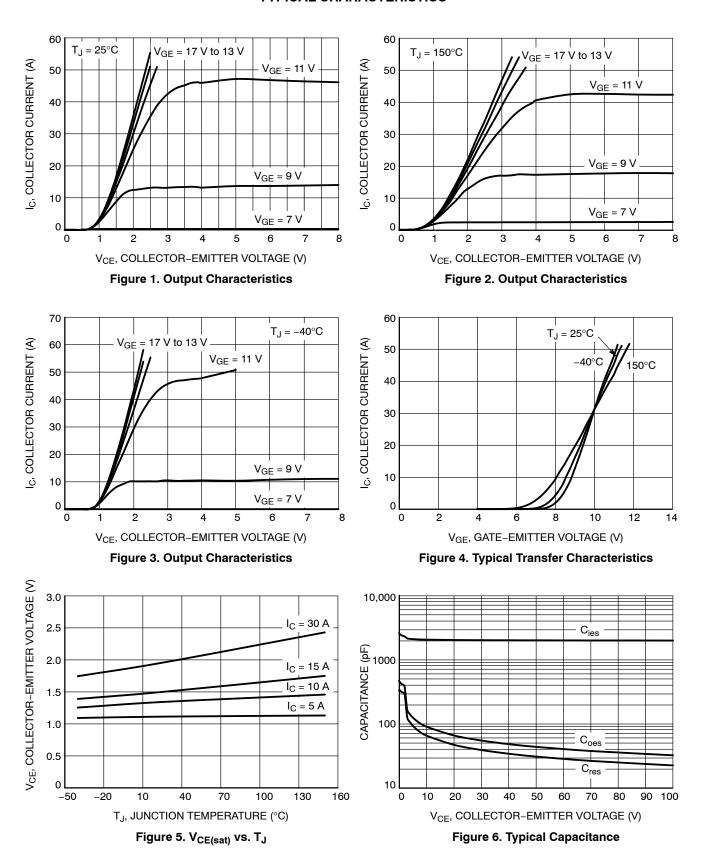
Rating	Symbol	Value	Unit
Thermal resistance junction to case, for IGBT	$R_{ heta JC}$	1.06	°C/W
Thermal resistance junction to case, for Diode	$R_{ hetaJC}$	3.76	°C/W
Thermal resistance junction to ambient	$R_{ hetaJA}$	60	°C/W

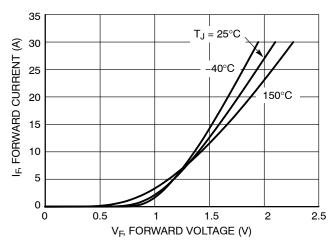
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC		•				
Collector-emitter breakdown voltage, gate-emitter short-circuited	V_{GE} = 0 V, I_C = 500 μA	V _{(BR)CES}	600	-	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V , I _C = 15 A V _{GE} = 15 V , I _C = 15 A, T _J = 150°C	V _{CEsat}	1.3 1.55	1.5 1.75	1.7 1.95	٧
Gate-emitter threshold voltage	V_{GE} = V_{CE} , I_C = 250 μA	V _{GE(th)}	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate-emitter short-circuited	V _{GE} = 0 V, V _{CE} = 600 V V _{GE} = 0 V, V _{CE} = 600 V, T _J = 150°C	I _{CES}	- -	10 -	- 200	μΑ
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V		=	-	100	nA
Forward Transconductance	$V_{CE} = 20 \text{ V}, I_{C} = 15 \text{ A}$	9fs	-	10.1	-	S
DYNAMIC CHARACTERISTIC		•				
Input capacitance		C _{ies}	_	1950	-	
Output capacitance	V_{CE} = 20 V, V_{GE} = 0 V, f = 1 MHz	C _{oes}	-	70	-	pF
Reverse transfer capacitance		C _{res}	-	42	-	
Gate charge total		Q_g	_	88	-	
Gate to emitter charge	V_{CE} = 480 V, I_{C} = 15 A, V_{GE} = 15 V	Q_{ge}	-	16	-	nC
Gate to collector charge		Q_{gc}	-	42	-	
SWITCHING CHARACTERISTIC , INDUCTIVE	LOAD					
Turn-on delay time		t _{d(on)}	-	65	-	ns
Rise time		t _r	-	28	-	
Turn-off delay time	T _J = 25°C	t _{d(off)}	-	170	-	
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 15 \text{ A}$ $R_{g} = 22 \Omega$	t _f	-	140	-	
Turn-on switching loss	$V_{GE} = 0 V / 15 V$	E _{on}	-	0.550	-	
Turn-off switching loss		E _{off}	-	0.350	_	mJ
Total switching loss		E _{ts}	-	0.900	-	
Turn-on delay time		t _{d(on)}	-	65	_	
Rise time		t _r	-	28	_	20
Turn-off delay time	T _J = 150°C	t _{d(off)}	-	180	-	ns
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 15 \text{ A}$ $R_g = 22 \Omega$	t _f	-	260	-	
Turn-on switching loss	$V_{GE} = 0 \text{ V} / 15 \text{ V}$	E _{on}	-	0.650	-	
Turn-off switching loss		E _{off}	-	0.600	-	mJ
Total switching loss		E _{ts}	-	1.250	-	
DIODE CHARACTERISTIC		•				
Forward voltage	V _{GE} = 0 V, I _F = 15 A V _{GE} = 0 V, I _F = 15 A, T _J = 150°C	V _F	- -	1.65 1.75	1.85 -	V

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
DIODE CHARACTERISTIC						
Reverse recovery time	T _{.1} = 25°C	t _{rr}	_	270	_	ns
Reverse recovery charge	$I_F = 15 \text{ A}, V_R = 200 \text{ V}$	Q _{rr}	_	350	-	nc
Reverse recovery current	di _F /dt = 200 A/μs	I _{rrm}	_	5	-	Α
Reverse recovery time	T _J = 125°C	t _{rr}	_	350	-	ns
Reverse recovery charge	$I_{E} = 15 \text{ A}. V_{P} = 200 \text{ V}$	Q _{rr}	_	1000	-	nc
Reverse recovery current	di _F /dt = 200 A/μs	I _{rrm}	-	7.5	-	Α

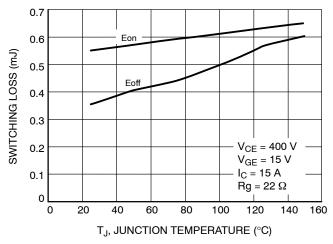




20 V_{GE}, GATE-EMITTER VOLTAGE (V) 15 V_{CES} = 480 V 10 5 10 20 40 50 60 70 80 90 100 0 Q_G, GATE CHARGE (nC)

Figure 7. Diode Forward Characteristics

Figure 8. Typical Gate Charge



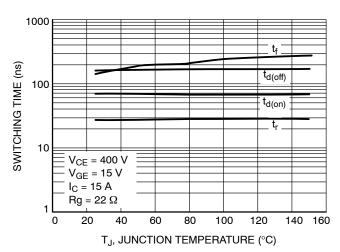
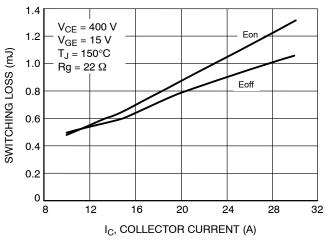


Figure 9. Switching Loss vs. Temperature

Figure 10. Switching Time vs. Temperature



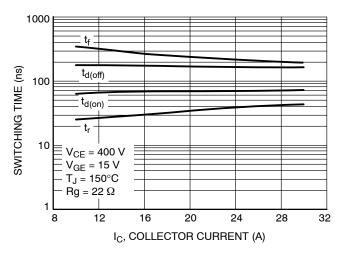


Figure 11. Switching Loss vs. I_C

Figure 12. Switching Time vs. I_C

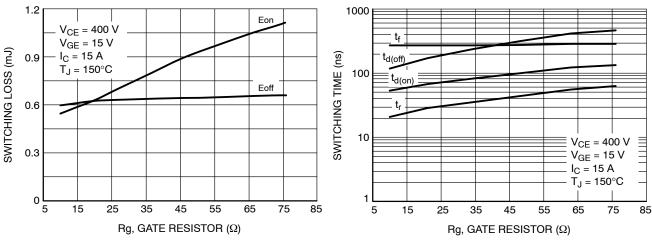


Figure 13. Switching Time vs. Rg

Figure 14. Switching Time vs. Rg

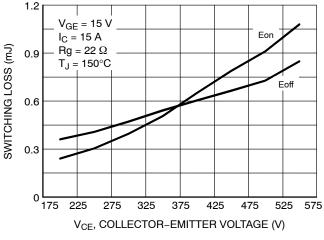


Figure 15. Switching Loss vs. V_{CE}

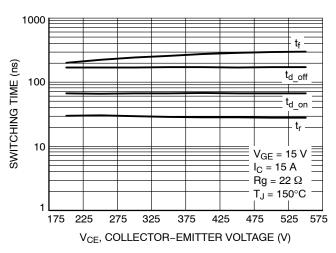
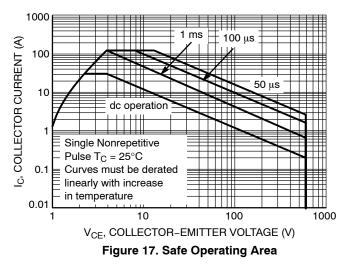


Figure 16. Switching Time vs. V_{CE}



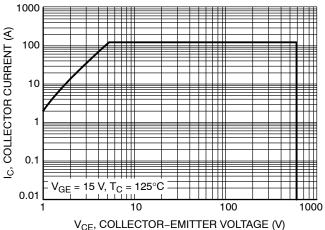


Figure 18. Reverse Bias Safe Operating Area

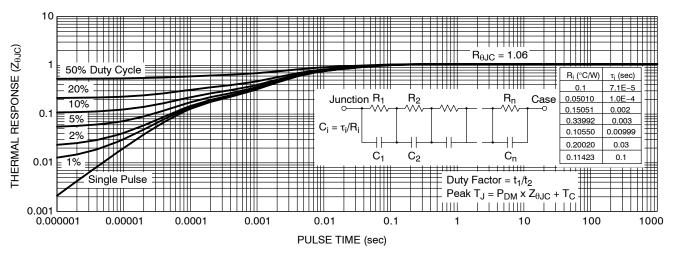


Figure 19. IGBT Transient Thermal Impedance

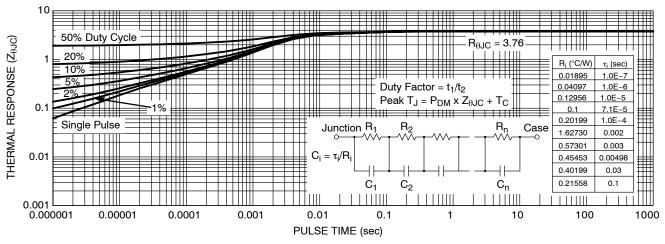


Figure 20. Diode Transient Thermal Impedance

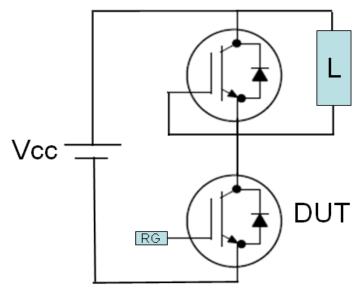


Figure 21. Test Circuit for Switching Characteristics

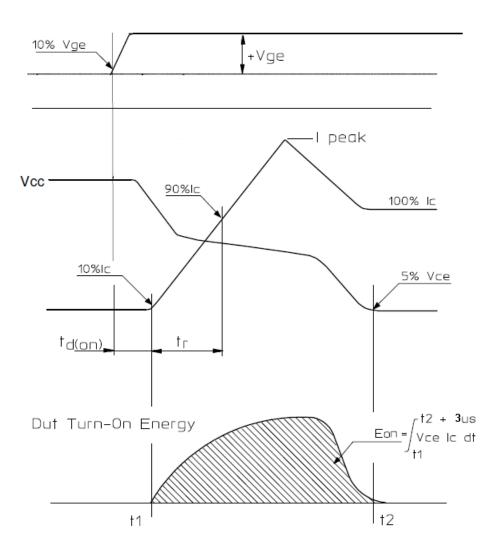


Figure 22. Definition of Turn On Waveform

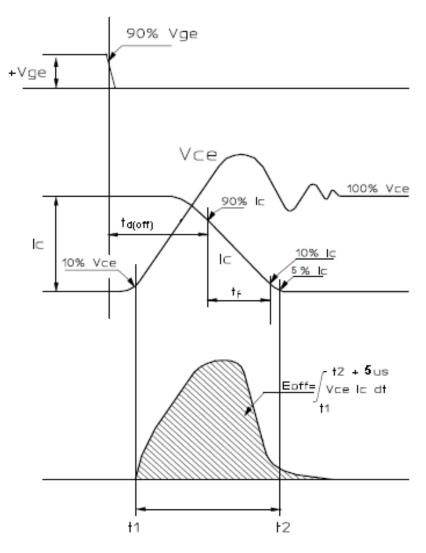
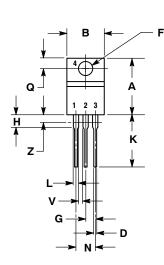
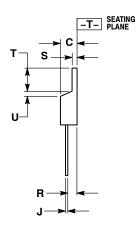


Figure 23. Definition of Turn Off Waveform

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AG**





- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE

	INC	MILLIM	IETEDS		
			MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.036	0.64	0.91	
F	0.142	0.161	3.61	4.09	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.161	2.80	4.10	
J	0.014	0.025	0.36	0.64	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
T	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Z		0.080		2.04	

STYLE 9:

- PIN 1. GATE
 - COLLECTOR
 - **EMITTER** COLLECTOR

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